



Material Content Data Sheet



Sales Product Name				IDFW60C65D1		Issued		1. August 2018	
MA#				MA002067510					
Package				PG-HSIP247-3-1		Weight*		5788.52 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	1.381	0.02	0.02	239	239	
chip_2	inorganic material	silicon	7440-21-3	1.381	0.02	0.02	239	239	
leadframe	inorganic material	phosphorus	7723-14-0	0.164	0.00		28		
	non noble metal	iron	7439-89-6	0.545	0.01		94		
wire	non noble metal	copper	7440-50-8	544.561	9.41	9.42	94076	94198	
	non noble metal	aluminium	7429-90-5	14.521	0.25	0.25	2509	2509	
encapsulation	inorganic material	zinc oxide	1314-13-2	0.235	0.00		41		
	plastics	silicone resin	-	0.530	0.01		92		
	inorganic material	alumina	1344-28-1	5.121	0.09		885		
	organic material	carbon black	1333-86-4	21.909	0.38		3785		
	plastics	epoxy resin	-	416.272	7.19		71913		
leadfinish	inorganic material	silicon dioxide	60676-86-0	1752.723	30.28	37.95	302793	379509	
	non noble metal	tin	7440-31-5	16.291	0.28	0.28	2814	2814	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.456	0.01	0.01	79	80	
solder	non noble metal	antimony	7440-36-0	0.234	0.00		40		
	noble metal	silver	7440-22-4	0.585	0.01		101		
	non noble metal	tin	7440-31-5	1.521	0.03	0.04	263	404	
heatspreader	inorganic material	phosphorus	7723-14-0	0.903	0.02		156		
	non noble metal	iron	7439-89-6	3.010	0.05		520		
	non noble metal	copper	7440-50-8	3006.169	51.94	52.01	519332	520008	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com